

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	102	("5861632" "5972728" "5672449" "6052185" "6060374" "5970313" "6033922" "6166354" "5869372" "4805187" "4755049" "4799392" "5451529" "6221726" "6221726" "6462817" "4868537" "4584026" "4968634" "5213986" "5580816" "4242791" "4417347" "4421479" "4433246" "4486652" "4523963" "4617066" "5614433" "5773355" "5985728" "6013546" "6124156" "4436581" "4435895" "4767721" "4877962" "4946735" "4952446" "5334543" "5489541" "5585297" "5654210" "5753956" "5858864" "5882947" "5885873" "5895237" "5950079" "5960284").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/21 15:47
S2	2	"4181538".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/21 15:46
S3	2	"6818459".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 19:33
S4	490	amorphous adj silicon and monitoring and implantation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 12:53
S5	23	amorphous adj silicon same monitoring and implantation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 13:09
S6	13	amorph\$9 adj silicon same monitor\$4 adj (substrate or chip or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/26 13:10
S7	61	"4181538"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 15:45

S8	0	laluo same dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 19:33
S9	2611	lanthanum same dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 19:34
S10	55	lanthanum same lutetium same dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/07 19:35
S11	60	lanthanum same lutetium same dielectric	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 19:41
S12	5	"LaLuO.sub.3"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/07 19:41
S13	1	"20050124080".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 15:40
S14	2	"5770512".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 15:51
S15	1722	438/796.ccls.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 15:49
S16	1	438/796.ccls. and monitor\$4 adj wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 16:01
S17	1	438/796.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 16:04

S18	2	438/486.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:09
S19	5	438/308.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:15
S20	12	438/476.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:16
S21	17	438/795.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:17
S22	0	438/797.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/14 16:05
S23	3	438/798.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:17
S24	3	438/799.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:18
S25	2	"6818459".pn.	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/14 18:14
S26	2004	(438/14).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 14:53
S27	2002	(438/14).CCLS.	US-PGPUB; USPAT; EPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 14:54
S28	2002	(438/14).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/20 14:54

S29	2004	(438/14).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 15:28
S30	781	(438/15).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 15:38
S31	1076	(438/16).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 15:38
S32	1735	438/796.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/20 15:49
S33	2	438/486.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:09
S34	569	438/486.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:09
S35	5	438/308.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:16
S36	370	438/308.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:20
S37	12	438/476.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:18
S38	558	438/476.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:25

S39	17	438/795.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:19
S40	920	438/795.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:32
S41	3	438/798.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:19
S42	385	438/798.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:41
S43	3	438/799.ccls. and monitor\$4 adj (wafer or chip or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:20
S44	218	438/799.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/20 16:45